



How AI & Semiconductors will Drive Innovation & Productivity

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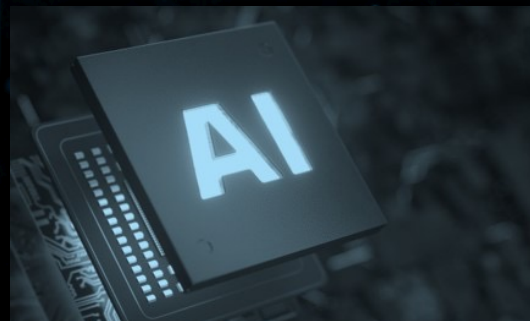
CVP AI Product Management
AI Group

AI Challenges



More than Moore

Exponential compute & data growth post Moore



Endpoint to Cloud

HW Architecture scaling battery-powered to cloud



Sustainability

The Imperative of Higher Perf/Watt



Safety, Bias, Compliance

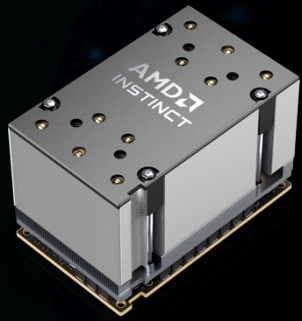
Safe & permissible data, model, software

AMD

AI Platforms

AI Hardware Portfolio

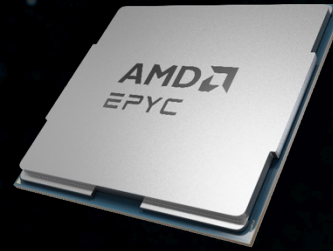
Data center | Edge | End point



AMD Instinct™
GPUs



AMD Alveo™
AI Accelerators



AMD EPYC™
Server Processors



AMD Embedded
Versal™ AI Edge



AMD Ryzen™ AI
Mobile Processors

Architectures

CDNA [+Zen]

XDNA

Zen

XDNA

Zen +RDNA +XDNA

AI Models and Algorithms



Ecosystem



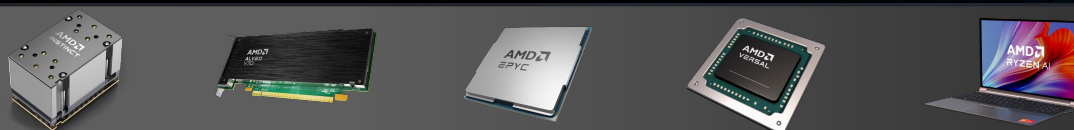
Libraries

Unified AI Frontend

Compilers and Tools

ROCm ZenDNN Vitis AI

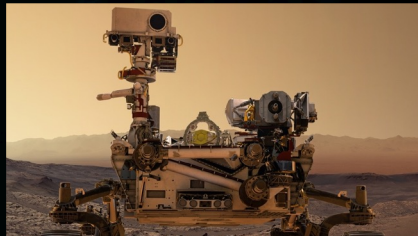
Runtime



Platforms

AMD AI Platforms

Powering Edge to Cloud AI



Aerospace



Automotive



Healthcare



Industrial



Communications



Smart PCs




Data Center




 #1 Frontier



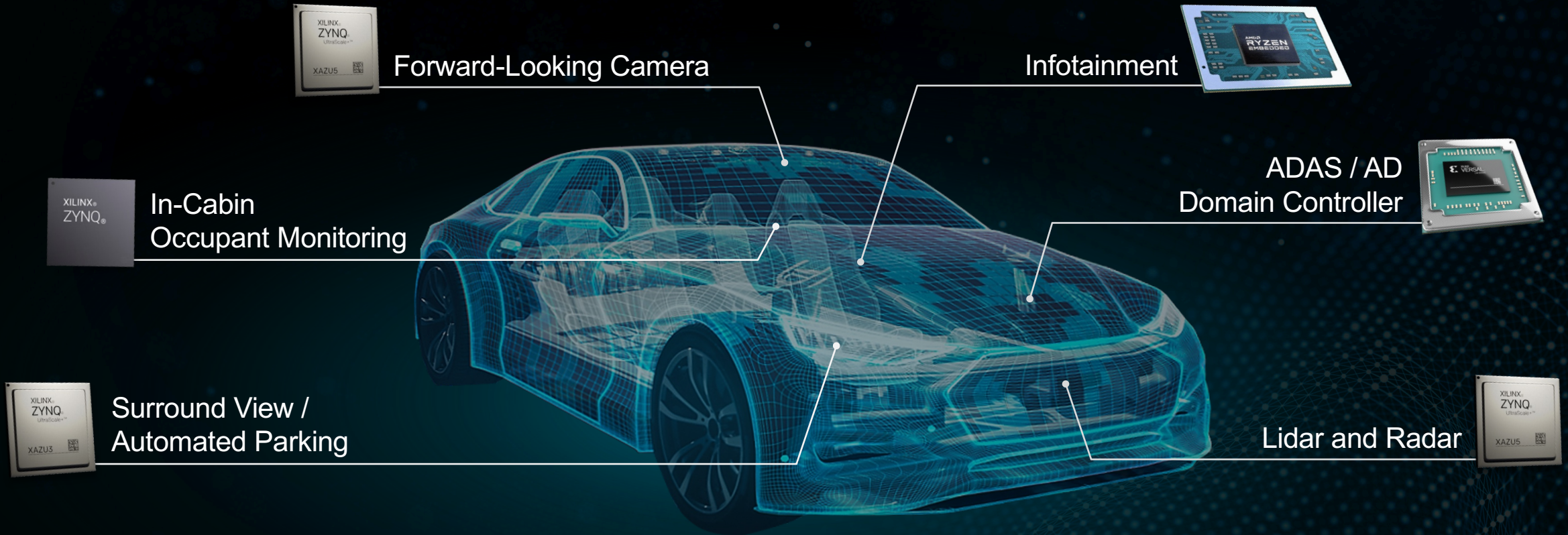
 #3 LUMI



 #11 Explorer

Supercomputers

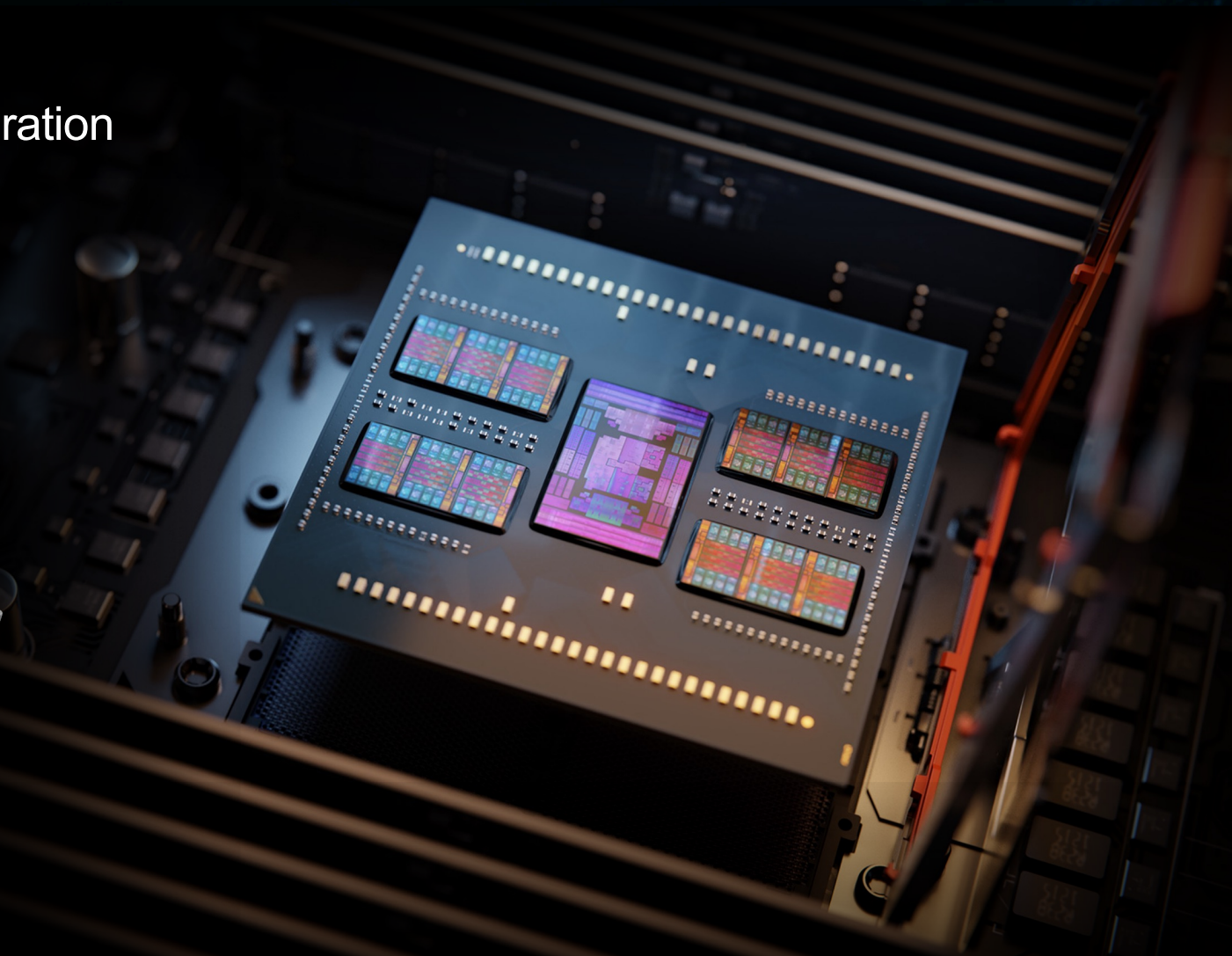
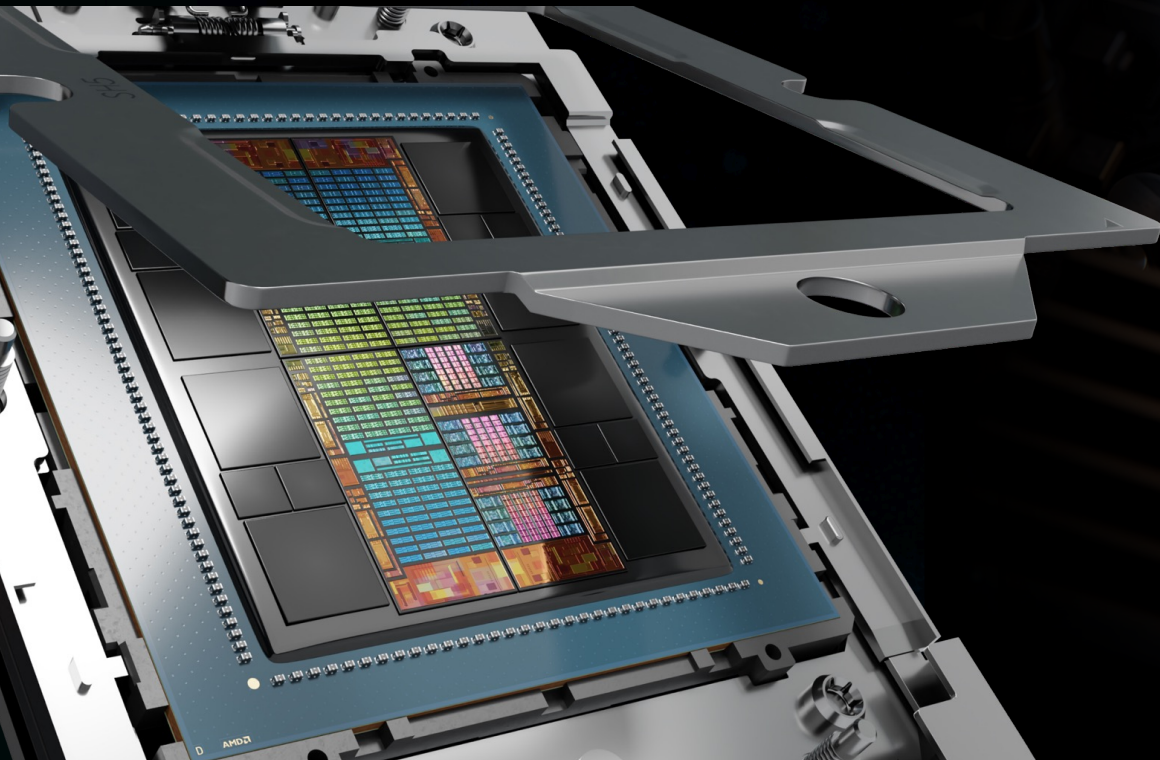
AI Everywhere: Real-World Application



Technology Advancements Boosting AI

Advanced Packaging: Chiplets, 3D Integration

- Increased compute & SRAM density
- Expanded HBM capacity
- Product agility & improved yield

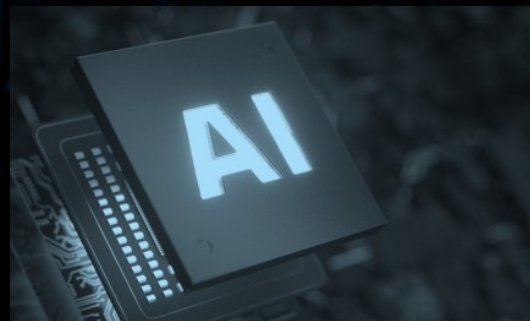


Addressing AI Challenges



More than Moore

Domain Specific Architecture (DSA) for AI workloads



Endpoint to Cloud

Diverse DSA variations & optimization points



Sustainability

Leadership Energy-Efficiency via Chiplet and 3D integration



Safety, Bias, Compliance

Open ecosystem
Open-source community

AMD 